

10/509,754

**AMENDMENT TO THE CLAIMS:**

1. (Currently amended) A method of manufacturing boards, the method comprising  
steps of ~~uses a prepreg and a metal foil to be laminated in laminating, the laminating comprising:~~  
laminating a metal foil on one face of a prepreg sheet;  
placing a mold-releasing sheet on another face of the prepreg sheet;  
heating and pressing a given place of the prepreg sheet and the metal foil ~~at a given place~~  
via ~~[[a]]~~ the mold-releasing sheet by a partial heat and press means, after the placing step;  
~~removing the heat and the press applied by the heat and press means;~~  
~~cooling the prepreg and the metal foil, then peeling off the mold-releasing sheet, after~~  
heating and pressing the given place, and

heating and pressing an entire face of the prepreg sheet and the metal foil, after the  
peeling off step,

wherein, the heating and pressing the given place prepreg and the metal foil at a given  
place are performed at a temperature not lower than a softening point of a resin impregnated into  
the prepreg sheet, while the temperature allows the resin to be kept in stage-B status.

2. (Currently amended) A method of manufacturing boards comprising steps of:  
laminating a first metal foil on one face of a first prepreg sheet on a first metal foil;  
placing a mold-releasing sheet on another face of the first prepreg sheet;  
heating and pressing ~~the prepreg at a first given place for bonding of~~ the first prepreg  
sheet and the first metal foil via the mold-releasing sheet by a partial heat and press means  
together;  
peeling off the mold-releasing sheet after heating and pressing the first given place;

10/509,754

laminating a board having a circuit pattern on the another face of the first prepreg sheet,  
after the peeling off step;

heating and pressing ~~the board at a~~ second given place ~~of for bonding~~ the first prepreg  
sheet and the board, after laminating the board together;

laminating a second prepreg sheet on the board, after heating and pressing the second  
given place;

heating and pressing ~~the second prepreg at a~~ third given place ~~of for bonding~~ the ~~another~~  
second prepreg sheet and the board, after laminating the second prepreg sheet together;

laminating a second metal foil on the second prepreg sheet, after heating and pressing the  
third given place;

heating and pressing ~~the second metal foil at a~~ fourth given place ~~for bonding of the~~  
second metal foil and the second prepreg sheet together to form a laminate; and

heating and pressing an entire face of the first prepreg sheet, the first metal foil, the  
board, the second prepreg sheet, and the second metal foil, after heating and pressing the fourth  
given place to bond the laminate together,

wherein the heating and pressing ~~[[at]]~~ the first given place to fourth given place is  
performed includes: heating and pressing via a mold-releasing sheet by a heat and press means at  
a temperature not lower than a softening point of a resin impregnated into the first and the  
second prepreg sheet, while the temperature allows the resin to be kept in stage-B status;

~~removing the heat and press applied by the heat and press means; and~~  
~~cooling and peeling off the mold-releasing sheet.~~

3. (Cancelled)

**10/509,754**

4. (Previously presented) The manufacturing method as defined in claim 2, wherein the board having a circuit pattern is a composite of thermosetting resin and one of woven fiber or non-woven fiber.

5-6. (Cancelled)

7. (Previously presented) The manufacturing method as defined in claim 1 or claim 2, wherein the peeling off of the mold-releasing sheet includes peeling off the sheet from one end of the sheet toward another end.

8-28. (Cancelled)